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1 Block diagram and pin description

Figure 1. Simplified block diagram

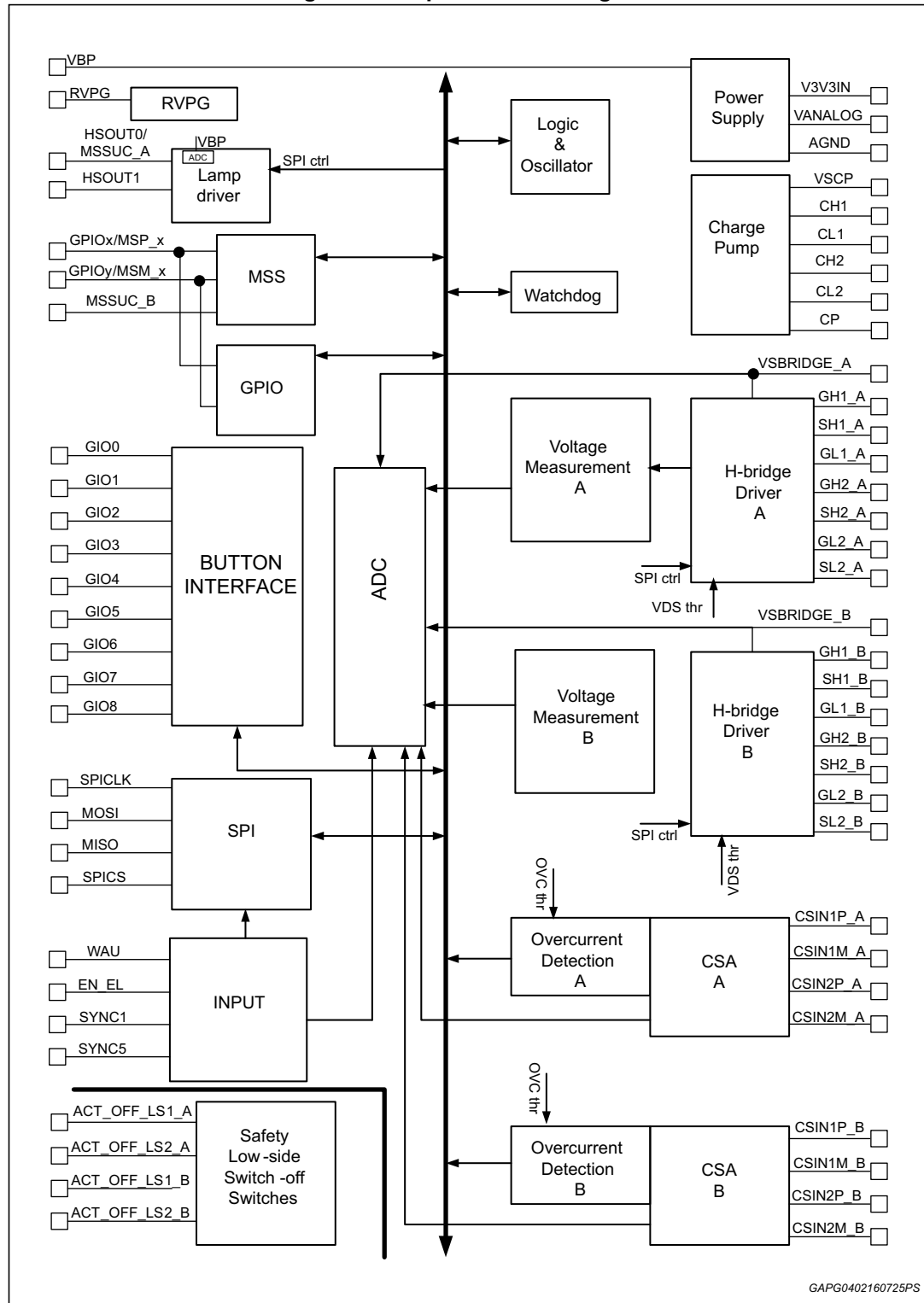
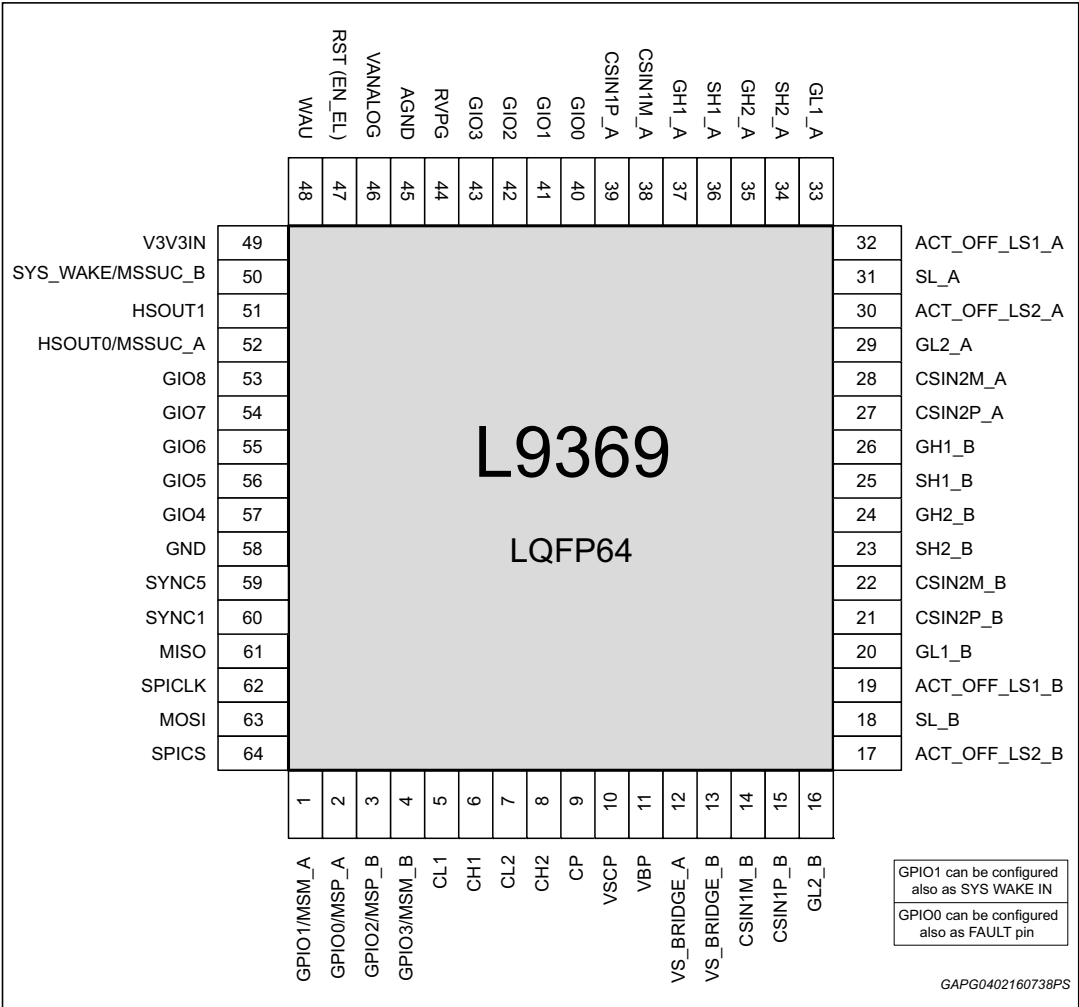


Figure 2. Pin out



PIN-out definition and related functions are described in the following [Table 2](#).

Table 2. Pin definition and brief function description

Pin #	Symbol	Function	I/O type
1	SYS_WAKE_IN / (GPIO1) / (MSM_A)	<p>SYS_WAKE_IN is a GPIO (General Purpose Programmable input/output) configured by default as digital input for system wake-up trigger in Sleep mode only. Configuration is stored in PROM. <i>(This function needs the SYS_WAKE as companion function to work properly, as SYS_WAKE_IN (feedback from ext network) is managed by logic to provide wake-up output pulse to System basis chip (SBC) during sleep mode (WAU=low). MSM_A is disabled due to pin sharing with GPIO block).</i></p> <p>GPIO1 = General Purpose Programmable input/output pin. After the 1st start-up SYS_WAKE_IN can be disabled via SPI in case not requested by application.</p> <p>MSM_A = Return pin for the motor speed sensor of stage A with monitoring and short-circuit protection. (SYS_WAKE_IN and GPIO1 functionalities are disabled)</p>	I/O
2	GPIO0 / MSP_A (FAULT PIN)	<p>GPIO0 = General Purpose Programmable input/output pin</p> <p>MSP_A = Supply pin for the motor speed sensor of stage A with monitoring short to GND protection and reverse supply protection</p> <p><i>(GPIO0 can be configured as Fault pin with programmable fault set via SPI and storage in PROM).</i></p>	I/O
3	GPIO2/MSP_B	<p>GPIO2 = General Purpose Programmable input/output pin</p> <p>MSP_B = Supply pin for the motor speed sensor of stage B with monitoring short to GND protection and reverse supply protection</p>	I/O
4	GPIO3/MSM_B	<p>GPIO3 = General Purpose Programmable input/output pin</p> <p>MSM_B = Return pin for the motor speed sensor of stage B with monitoring and short-circuit protection</p>	I/O
5	CL1	Low connection of the stage 1 external pump capacitor	I
6	CH1	High connection of the stage 1 external pump capacitor	I
7	CL2	Low connection of the stage 2 external pump capacitor	I
8	CH2	High connection of the stage 2 external pump capacitor	I
9	CP	Charge pump output voltage	O
10	VSCP	Charge pump supply voltage with monitoring	I
11	VBP	Battery supply and redundant supply for charge pump stage. <i>(Due to PROM data loss, configuration is lost if VBP < VBP_{permanent})</i>	I
12	VSBRIDGE_A	Drain connection of the external H-Bridge High-side NFET and measurement input for H-bridge supply voltage (stage A)	I
13	VSBRIDGE_B	Drain connection of the external H-Bridge High-side NFET and measurement input for H-bridge supply voltage (stage B)	I
14	CSIN1M_B	Negative input pin of the external shunt #1 connected to CSA stage B	I

Table 2. Pin definition and brief function description (continued)

Pin #	Symbol	Function	I/O type
15	CSIN1P_B	Positive input pin of the external shunt #1 connected to CSA stage B	I
16	GL2_B	Gate connection of the H-Bridge Low-side NFET for wheel brake actuator B	O
17	ACT_OFF_LS2_B	Safety LS switch-off switches for H-bridge stage B	I
18	SL_B	Source connection of the H-Bridge Low-side switches for wheel brake actuator B	I
19	ACT_OFF_LS1_B	Safety LS switch-off switches for stage H-bridge B	I
20	GL1_B	Gate connection of the H-Bridge Low-side NFET for right wheel brake actuator B	I
21	CSIN2P_B	Positive input signal of the external shunt #2 connected to redundant CSA for stage B	I
22	CSIN2M_B	Negative input signal of the external shunt #2 connected to redundant CSA for stage B	I
23	SH2_B	Source connection of the H-Bridge High-side NFET for wheel brake actuator B	I
24	GH2_B	Gate connection of the H-Bridge High-side NFET for wheel brake actuator B	O
25	SH1_B	Source connection of the H-Bridge High-side NFET for wheel brake actuator B	I
26	GH1_B	Gate connection of the H-Bridge High-side NFET for wheel brake actuator B	O
27	CSIN2P_A	Positive input signal of the external shunt #2 connected to redundant CSA stage for A	I
28	CSIN2M_A	Negative input signal of the external shunt #2 connected to redundant CSA for stage A	I
29	GL2_A	Gate connection of the H-Bridge Low-side NFET for wheel brake actuator A	O
30	ACT_OFF_LS2_A	Safety LS switch-off switch for stage H-bridge A	I
31	SL_A	Source connection of the H-Bridge Low-side switches for wheel brake actuator A	I
32	ACT_OFF_LS1_A	Safety LS switch-off switch for stage H-bridge A	I
33	GL1_A	Gate connection of the H-Bridge Low-side NFET for wheel brake actuator A	O
34	SH2_A	Source connection of the H-Bridge High-side NFET for wheel brake actuator A	I
35	GH2_A	Gate connection of the H-Bridge High-side NFET for wheel brake actuator A	O
36	SH1_A	Source connection of the H-Bridge High-side NFET for wheel brake actuator A	I

Table 2. Pin definition and brief function description (continued)

Pin #	Symbol	Function	I/O type
37	GH1_A	Gate connection of the H-Bridge High-side NFET for wheel brake actuator A	O
38	CSIN1M_A	Negative input signal of the external shunt #1 connected to CSA for stage A	I
39	CSIN1P_A	Positive input signal of the external shunt #1 connected to CSA for stage A	I
40	GIO0	Programmable Input / Output for Button Interface control	I/O
41	GIO1	Programmable Input / Output for Button Interface control	I/O
42	GIO2	Programmable Input / Output for Button Interface control	I/O
43	GIO3	Programmable Input / Output for Button Interface control	I/O
44	RVPG	Gate driver output for reverse voltage switch control	O
45	AGND	Analog reference ground connection	GND
46	VANALOG	L9369 generated Low noise analog voltage, supplies the internal current measurement path. <i>(It can be used to supply external circuits with low current consumption. External capacitor required for stabilization.)</i>	O
47	RST (EN_EL)	EN_EL : digital enable input for GPIO (default pin function). RST : High active Input Reset pin. <i>(Enabled via dedicated SPI bit. GPIO block can be enabled and configured independently)</i>	I
48	WAU	Wake-up input. <i>(digital input, low level active to enter Sleep Mode)</i>	I
49	V3V3VIN	3.3 V supply voltage for L9369 output buffers	I
50	SYS_WAKE/MSSUC_B	SYS WAKE (default configuration at start-up) is a digital output pin to wake System basis chip (SBC) up as support for general diagnostics on the external button during Sleep Mode only. This function/pin needs the SYS_WAKE_IN as companion function to work properly. MSSUC_B is disabled due to pin sharing with GPIO block. In case the SYS_WAKE function is not requested by application, It can be disabled via SPI at 1 st start-up and the pin can be configured as: MSSUC_B = Motor speed sensor signal output to the μ C. <i>(MSS interface is disabled by default and its functionality is shared with Lamp driver HSOUT).</i>	O
51	HSOUT1	HSOUT1 = SPI programmable HS/LS current source for external bulb lamp or LED array with monitoring	O
52	HSOUT0/MSSUC_A	HSOUT0 = SPI programmable HS/LS current source for external bulb lamp or LED array with monitoring MSSUC_A = Motor speed sensor signal output to the μ C. <i>MSS interface is disabled by default.</i>	O
53	GIO8	Programmable Input / Output for Button Interface control	I/O

Table 2. Pin definition and brief function description (continued)

Pin #	Symbol	Function	I/O type
54	GIO7	Programmable Input / Output for Button Interface control	I/O
55	GIO6	Programmable Input / Output for Button Interface control	I/O
56	GIO5	Programmable Input / Output for Button Interface control	I/O
57	GIO4	Programmable Input / Output for Button Interface control	I/O
58	GND	Digital and power ground connection	GND
59	SYNC5	Synchronization signal from μC for ADC voltage/current measurement path	I
60	SYNC1	Synchronization signal from μC for ADC voltage/current measurement path	I
61	MISO	Serial data out for SPI communication to μC	O
62	SPICLK	Clock signal for SPI	I
63	MOSI	Serial data input for SPI communication from μC	I
64	SPICS	Chip select for SPI	I

Table 3. General conditions

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit	Parameter ID
T_{junction}	Function temperature	(parameters guaranteed)	-40	-	175	$^{\circ}\text{C}$	L9369_194
R_{th}	Application specific R_{th}	(Housing mounted on 6-Layer PCB)	-	-	40	$^{\circ}\text{C/W}$	L9369_3052

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

2.1 LQFP64 (10x10x1.4 mm) package information

Figure 3. LQFP64 (10x10x1.4 mm) package outline

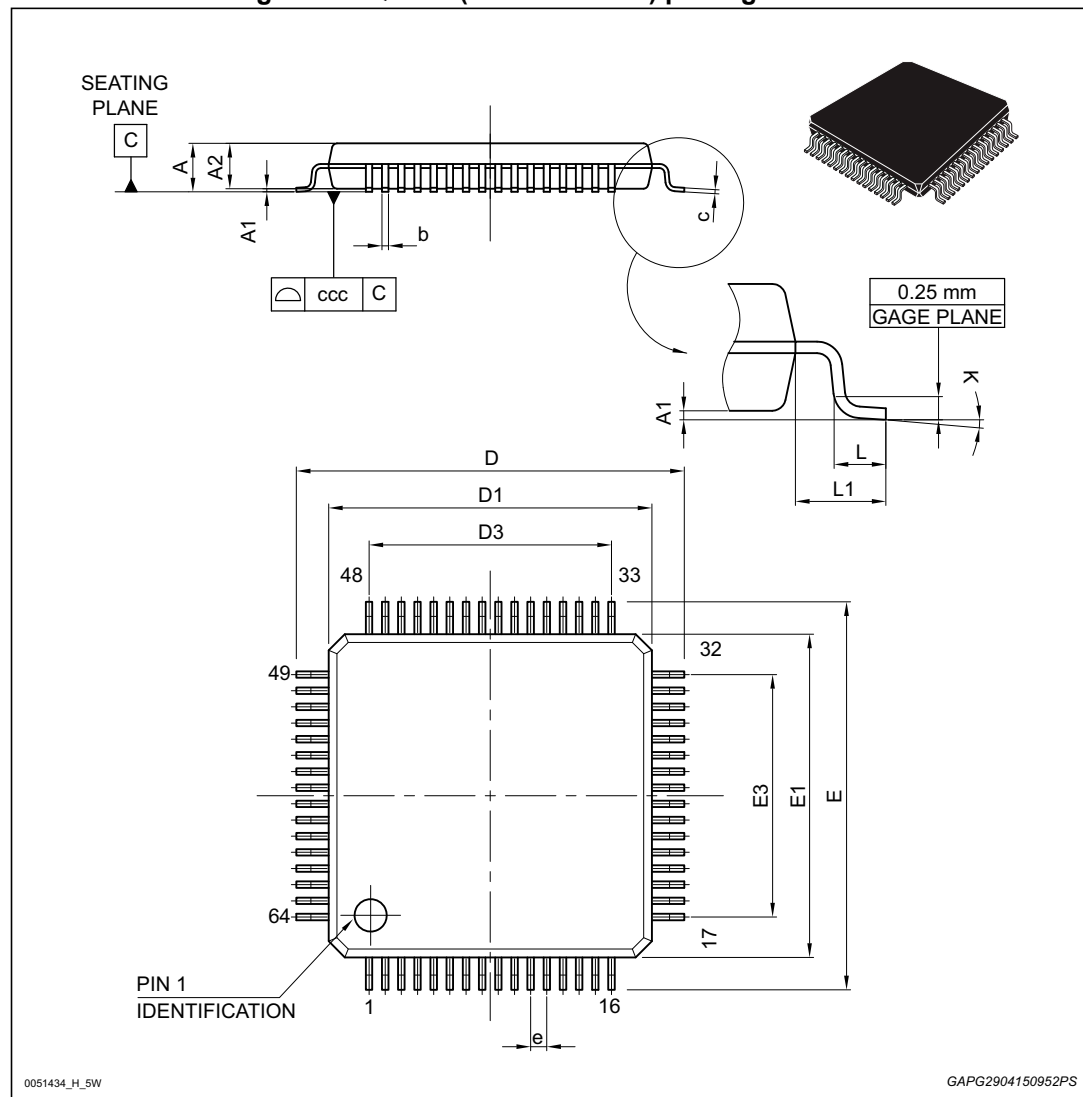


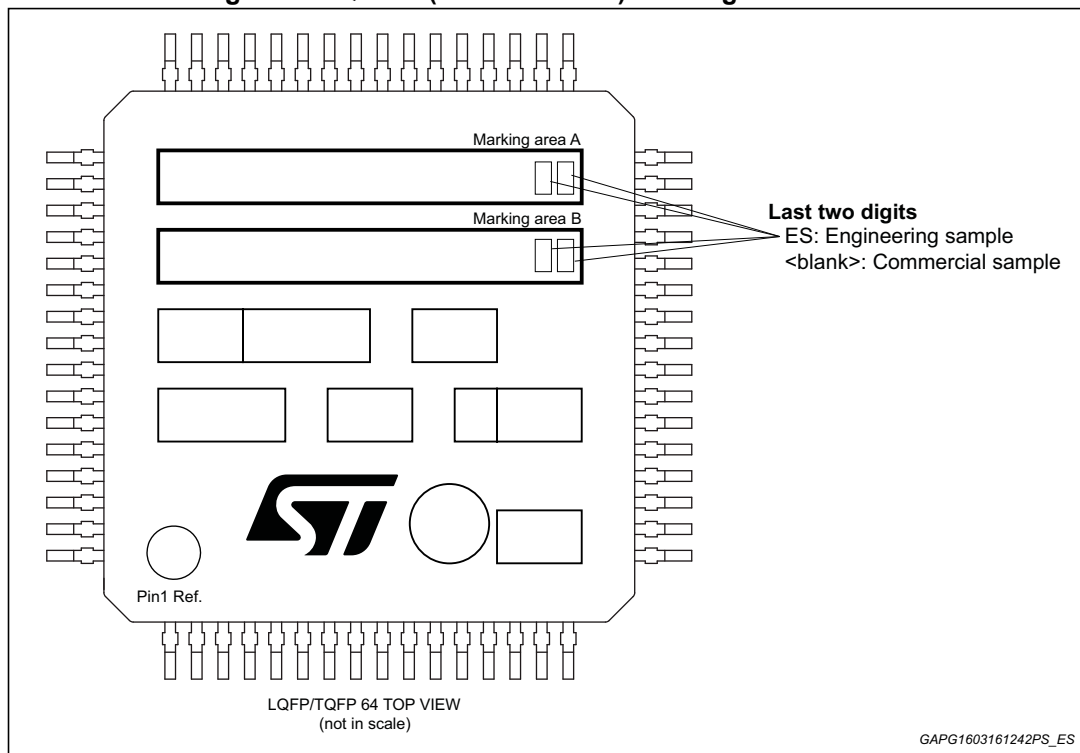
Table 4. LQFP64 (10x10x1.4 mm) package mechanical data

Ref	Dimensions					
	Millimeters			Inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.60	-	-	0.0630
A1	0.05	-	0.15	0.0020	-	0.0059
A2	1.350	1.40	1.45	0.0531	0.0551	0.0571
b	0.17	0.22	0.27	0.0067	0.0087	0.0106
c	0.09	-	0.20	0.0035	-	0.0079
D	11.80	12.00	12.20	0.4646	0.4724	0.4803
D1	9.80	10.00	10.20	0.3858	0.3937	0.4016
D3	-	7.50	-	-	0.2953	-
E	11.80	12.00	12.20	0.4646	0.4724	0.4803
E1	9.80	10.00	10.20	0.3858	0.3937	0.4016
E3	-	7.50	-	-	0.2953	-
e	-	0.50	-	-	0.0197	-
L	0.45	0.60	0.75	0.0177	0.0236	0.0295
L1	-	1.00	-	-	0.0394	-
K	0° (min.), 3.5° (typ.) 7° (max.)					
ccc	-	-	0.08	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

2.2 LQFP64 (10x10x1.4 mm) marking information

Figure 4. LQFP64 (10x10x1.4 mm) marking information



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3 Revision history

Table 5. Document revision history

Date	Revision	Changes
11-Jan-2019	1	Initial release.



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